Insulated Gate Bipolar Transistor (Ultrafast IGBT), 106 A



SOT-227

FEATURES

- Trench IGBT technology
- Square RBSOA
- HEXFRED® low Q_{rr}, low switching energy
- Positive $V_{CE(on)}$ temperature coefficient
- Fully isolated package
- Very low internal inductance (≤ 5 nH typical)
- Industry standard outline
- UL approved file E78996
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

Pb-free RoHS COMPLIANT

BENEFITS

- Designed for increased operating efficiency in power conversion: UPS, SMPS, welding, induction heating
- Easy to assemble and parallel
- Direct mounting on heatsink
- Plug-in compatible with other SOT-227 packages
- Low EMI, requires less snubbing

PRIMARY CHARACTERISTICS	
V_{CES}	1200 V
I_C DC	106 A at 90 °C
$V_{CE(on)}$ typical at 75 A, 25 °C	2.17 V
Speed	8 kHz to 30 kHz
Package	SOT-227
Circuit configuration	Single switch with AP diode

ABSOLUTE MAXIMUM RATINGS				
PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS
Collector to emitter voltage	V_{CES}		1200	V
Continuous collector current	I_C	T_C = 25 °C	169	A
		T_C = 90 °C	106	
Pulsed collector current	I_{CM}	T_J = 150 °C, t_p = 6 ms, V_{GE} = 15 V	350	
Clamped inductive load current	I_{LM}		250	
Diode continuous forward current	I_F	T_C = 25 °C	76	
		T_C = 90 °C	46	
Gate to emitter voltage	V_{GE}		± 20	V
Power dissipation, IGBT	P_D	T_C = 25 °C	781	W
		T_C = 90 °C	375	
Power dissipation, diode	P_D	T_C = 25 °C	357	
		T_C = 90 °C	171	
Isolation voltage	V_{ISOL}	Any terminal to case, t = 1 min	2500	V

For technical questions within your region: DiodesAmericas@vishay.com, DiodesAsia@vishay.com, DiodesEurope@vishay.com

THIS DOCUMENT IS SUBJECT TO CHANGE WITHOUT NOTICE. THE PRODUCTS DESCRIBED HEREIN AND THIS DOCUMENT ARE SUBJECT TO SPECIFIC DISCLAIMERS, SET FORTH AT www.vishay.com/doc?91000

ELECTRICAL SPECIFICATIONS (T_J = 25 °C unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Collector to emitter breakdown voltage	$V_{BR(CES)}$	V_{GE} = 0 V, I_C = 4 mA	1200	-	-	V
Collector to emitter voltage	$V_{CE(on)}$	V_{GE} = 15 V, I_C = 75 A	-	2.17	2.60	
		V_{GE} = 15 V, I_C = 75 A, T_J = 125 °C	-	2.44	-	
		V_{GE} = 15 V, I_C = 75 A, T_J = 150 °C	-	2.49	-	
Gate threshold voltage	$V_{GE(th)}$	V_{CE} = V_{GE}, I_C = 4 mA	4.6	5.9	7.6	
		V_{CE} = V_{GE}, I_C = 4 mA, T_J = 125 °C	-	4.63	-	
Temperature coefficient of threshold voltage	$V_{GE(th)}/\Delta T_J$	V_{CE} = V_{GE}, I_C = 4 mA (25 °C to 125 °C)	-	-13	-	mV/°C
Collector to emitter leakage current	I_{CES}	V_{GE} = 0 V, V_{CE} = 1200 V	-	0.9	100	µA
		V_{GE} = 0 V, V_{CE} = 1200 V, T_J = 125 °C	-	750	-	
		V_{GE} = 0 V, V_{CE} = 1200 V, T_J = 150 °C	-	2.7	-	mA
Forward voltage drop, diode	V_{FM}	V_{GE} = 0 V, I_F = 75 A	-	3.4	5.0	V
		V_{GE} = 0 V, I_F = 75 A, T_J = 125 °C	-	3.2	-	
		V_{GE} = 0 V, I_F = 75 A, T_J = 150 °C	-	3.05	-	
Gate to emitter leakage current	I_{GES}	V_{GE} = ± 20 V	-	-	± 250	nA

SWITCHING CHARACTERISTICS (T_J = 25 °C unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS
Total gate charge (turn-on)	Q_g	I_C = 90 A, V_{CC} = 960 V, V_{GE} = 15 V		-	307	-	nC
Gate to emitter charge (turn-on)	Q_{ge}			-	33	-	
Gate to collector charge (turn-on)	Q_{gc}			-	160	-	
Turn-on switching loss	E_{on}	I_C = 75 A, V_{CC} = 600 V, V_{GE} = 15 V, R_g = 5 Ω, L = 500 µH, T_J = 25 °C	Energy losses include tail and diode recovery Diode used HFA16PB120	-	2.15	-	mJ
Turn-off switching loss	E_{off}			-	2.59	-	
Total switching loss	E_{tot}			-	4.74	-	
Turn-on delay time	$t_{d(on)}$			-	36	-	ns
Rise time	t_r			-	26	-	
Turn-off delay time	$t_{d(off)}$			-	116	-	
Fall time	t_f			-	82	-	
Turn-on switching loss	E_{on}	I_C = 75 A, V_{CC} = 600 V, V_{GE} = 15 V, R_g = 5 Ω, L = 500 µH, T_J = 125 °C		-	2.23	-	mJ
Turn-off switching loss	E_{off}			-	3.87	-	
Total switching loss	E_{tot}			-	6.1	-	
Turn-on delay time	$t_{d(on)}$			-	34	-	ns
Rise time	t_r			-	27	-	
Turn-off delay time	$t_{d(off)}$			-	123	-	
Fall time	t_f			-	147	-	
Reverse bias safe operating area	RBSOA	T_J = 150 °C, I_C = 250 A, R_g = 4.7 Ω, V_{GE} = 15 V to 0 V, V_{CC} = 800 V, V_P = 1200 V, L = 500 µH		Fullsquare			
Diode reverse recovery time	t_{rr}	I_F = 50 A, dI_F/dt = 200 A/µs, V_R = 200 V		-	140	-	ns
Diode peak reverse current	I_{rr}			-	13	-	A
Diode recovery charge	Q_{rr}			-	860	-	nC
Diode reverse recovery time	t_{rr}	I_F = 50 A, dI_F/dt = 200 A/µs, V_R = 200 V, T_J = 125 °C		-	210	-	ns
Diode peak reverse current	I_{rr}			-	19	-	A
Diode recovery charge	Q_{rr}			-	1880	-	nC

THERMAL AND MECHANICAL SPECIFICATIONS

PARAMETER		SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Junction and storage temperature range		T_J, T_{Stg}		-40	-	150	°C
Junction to case	IGBT	R_{thJC}		-	-	0.16	°C/W
	Diode			-	-	0.35	
Case to heatsink		R_{thCS}	Flat, greased surface	-	0.05	-	
Weight				-	30	-	g
Mounting torque			Torque to terminal	-	-	1.1 (9.7)	Nm (lbf.in)
			Torque to heatsink	-	-	1.8 (15.9)	Nm (lbf.in)
Case style		SOT-227					

For technical questions within your region: DiodesAmericas@vishay.com, DiodesAsia@vishay.com, DiodesEurope@vishay.com
THIS DOCUMENT IS SUBJECT TO CHANGE WITHOUT NOTICE. THE PRODUCTS DESCRIBED HEREIN AND THIS DOCUMENT ARE SUBJECT TO SPECIFIC DISCLAIMERS, SET FORTH AT www.vishay.com/doc?91000

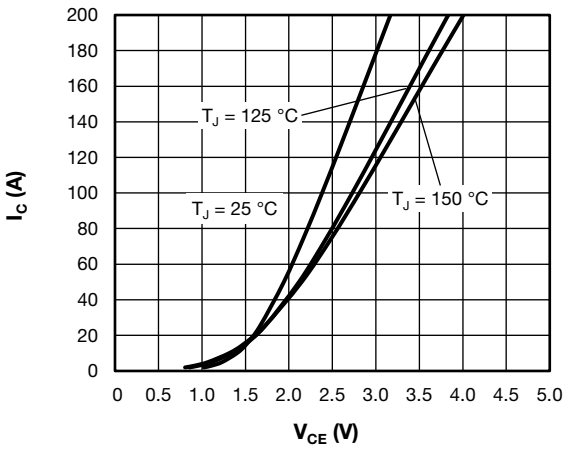


Fig. 1 - Typical Trench IGBT Output Characteristics, V_{GE} = 15 V

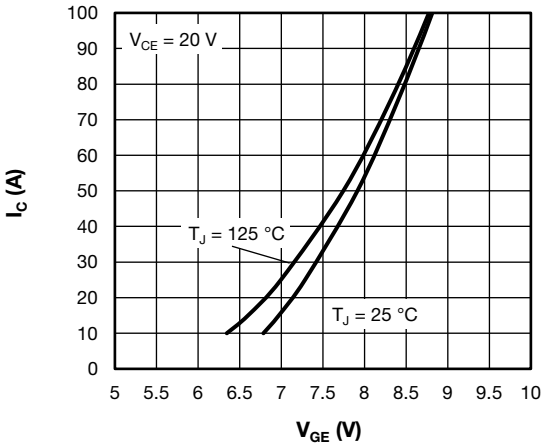


Fig. 4 - Typical Trench IGBT Transfer Characteristics

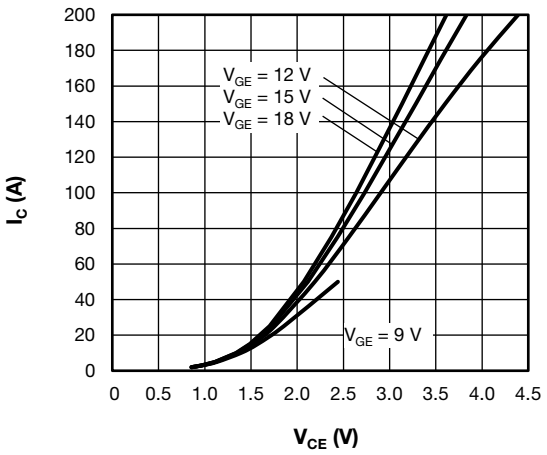


Fig. 2 - Typical Trench IGBT Output Characteristics, T_J = 125 °C

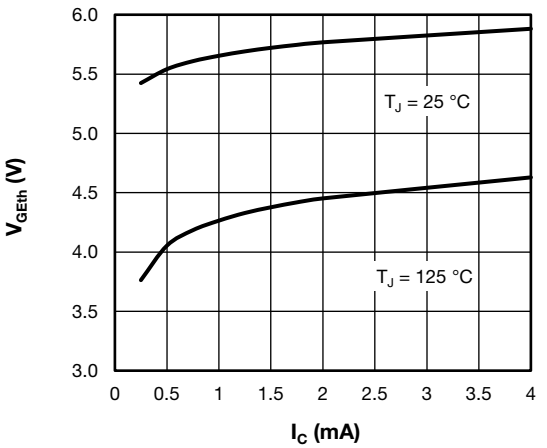


Fig. 5 - Typical Trench IGBT Gate Threshold Voltage

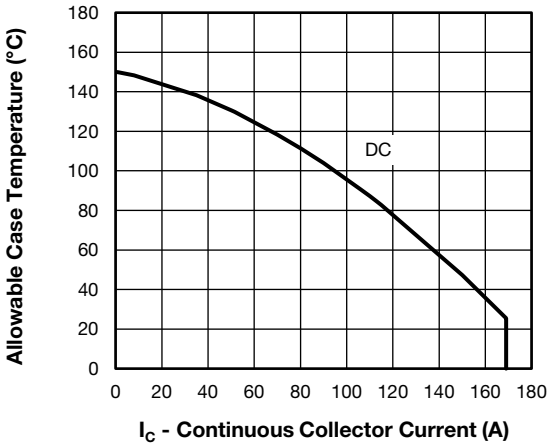


Fig. 3 - Maximum Trench IGBT Continuous Collector Current vs. Case Temperature

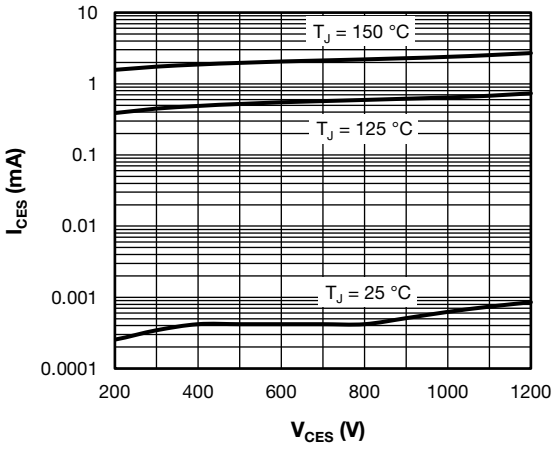


Fig. 6 - Typical Trench IGBT Zero Gate Voltage Collector Current

For technical questions within your region: DiodesAmericas@vishay.com, DiodesAsia@vishay.com, DiodesEurope@vishay.com
THIS DOCUMENT IS SUBJECT TO CHANGE WITHOUT NOTICE. THE PRODUCTS DESCRIBED HEREIN AND THIS DOCUMENT ARE SUBJECT TO SPECIFIC DISCLAIMERS, SET FORTH AT www.vishay.com/doc?91000

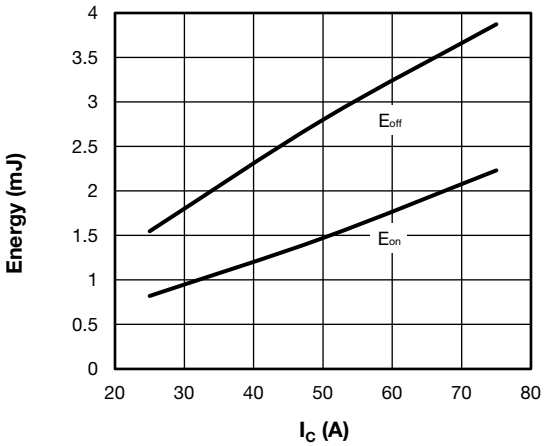


Fig. 7 - Typical Trench IGBT Energy Loss vs. I_C
(with Antiparallel Diode)
T_J = 125 °C, V_{CC} = 600 V, R_g = 4.7 Ω, V_{GE} = +15 V/-15 V, L = 500 µH

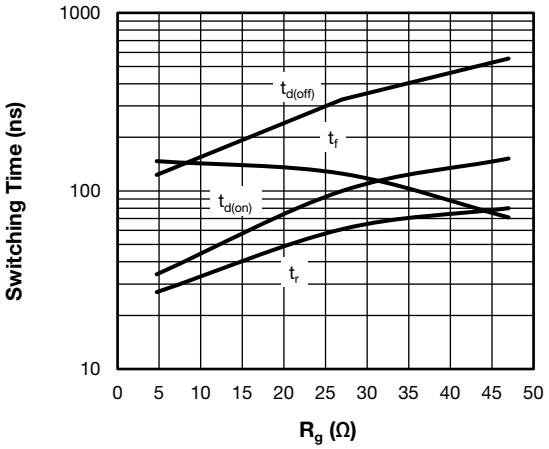


Fig. 10 - Typical Trench IGBT Switching Time vs. R_g
(with Antiparallel Diode)
T_J = 125 °C, V_{CC} = 600 V, I_C = 75 A, V_{GE} = +15 V/-15 V, L = 500 µH

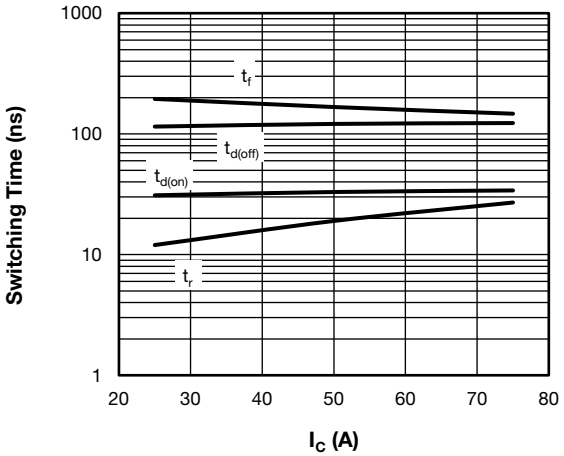


Fig. 8 - Typical Trench IGBT Switching Time vs. I_C
(with Antiparallel Diode)
T_J = 125 °C, V_{CC} = 600 V, R_g = 4.7 Ω, V_{GE} = +15 V/-15 V, L = 500 µH

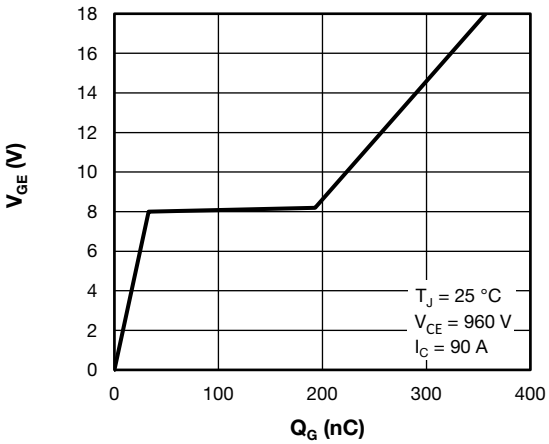


Fig. 11 - Typical Trench IGBT Gate Charge vs.
Gate to Emitter Voltage

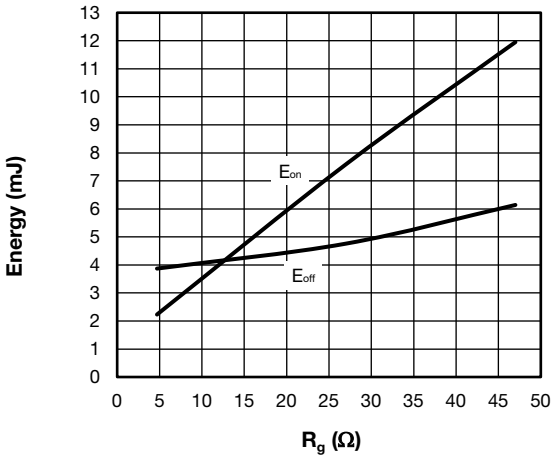


Fig. 9 - Typical Trench IGBT Energy Loss vs. R_g
(with Antiparallel Diode)
T_J = 125 °C, V_{CC} = 600 V, I_C = 75 A, V_{GE} = +15 V/-15 V, L = 500 µH

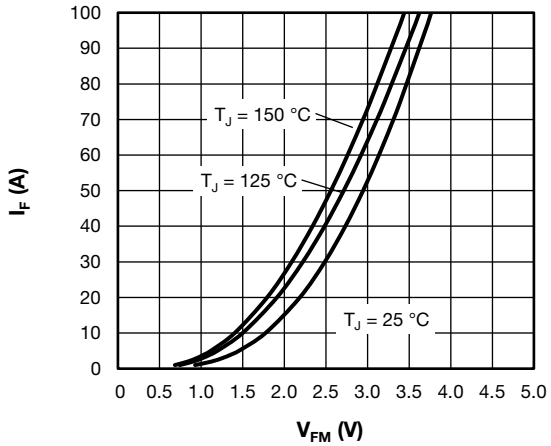


Fig. 12 - Typical Antiparallel Diode Forward Characteristics

For technical questions within your region: DiodesAmericas@vishay.com, DiodesAsia@vishay.com, DiodesEurope@vishay.com
THIS DOCUMENT IS SUBJECT TO CHANGE WITHOUT NOTICE. THE PRODUCTS DESCRIBED HEREIN AND THIS DOCUMENT ARE SUBJECT TO SPECIFIC DISCLAIMERS, SET FORTH AT www.vishay.com/doc?91000

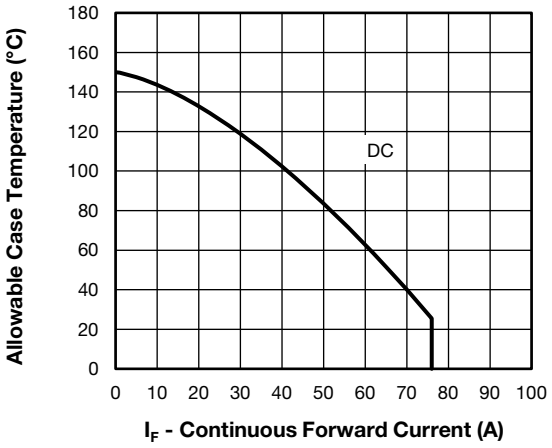


Fig. 13 - Maximum Antiparallel Diode Continuous Forward Current vs. Case Temperature

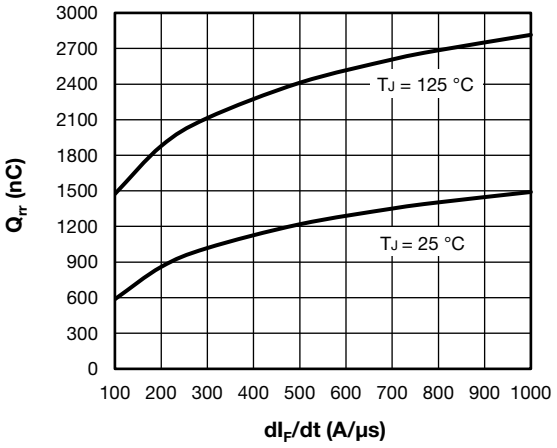


Fig. 16 - Typical Antiparallel Diode Reverse Recovery Charge vs. dI_F/dt, V_{rr} = 200 V, I_F = 50 A

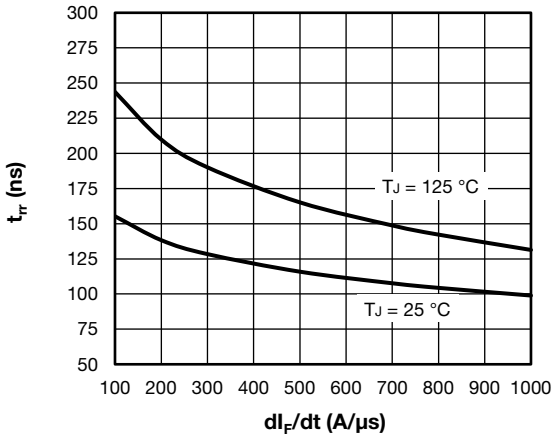


Fig. 14 - Typical Antiparallel Diode Reverse Recovery Time vs. dI_F/dt, V_{rr} = 200 V, I_F = 50 A

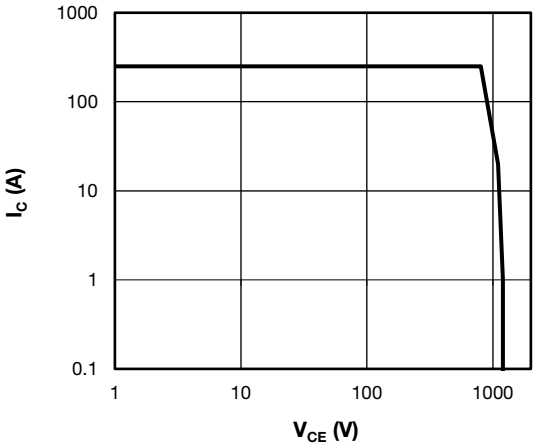


Fig. 17 - Trench IGBT Reverse BIAS SOA
T_J = 150 °C, V_{CC} = 800 V, I_C = 250 A, V_{GE} = +15 V/0, V_p = 1200 V

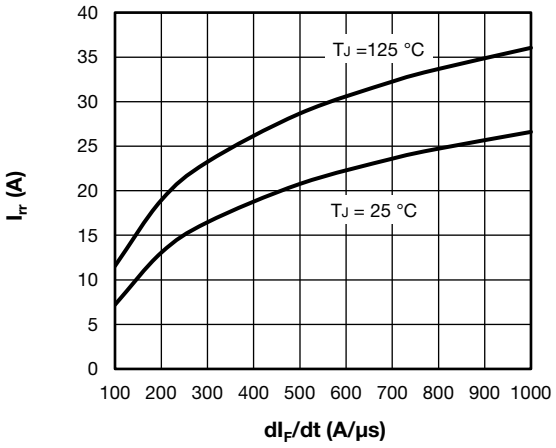


Fig. 15 - Typical Antiparallel Reverse Recovery Current vs. dI_F/dt V_{rr} = 200 V, I_F = 50 A

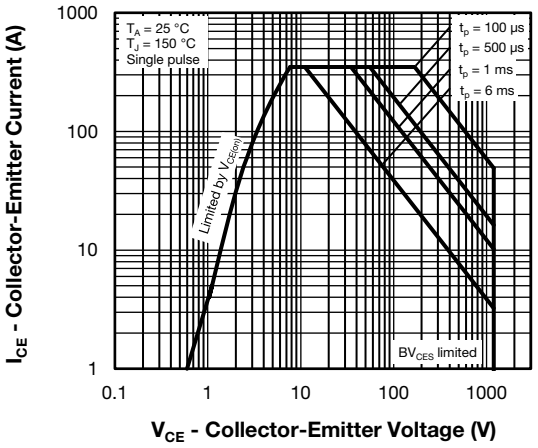


Fig. 18 - IGBT Reverse Bias Safe Operating Area

For technical questions within your region: DiodesAmericas@vishay.com, DiodesAsia@vishay.com, DiodesEurope@vishay.com
THIS DOCUMENT IS SUBJECT TO CHANGE WITHOUT NOTICE. THE PRODUCTS DESCRIBED HEREIN AND THIS DOCUMENT ARE SUBJECT TO SPECIFIC DISCLAIMERS, SET FORTH AT www.vishay.com/doc?91000

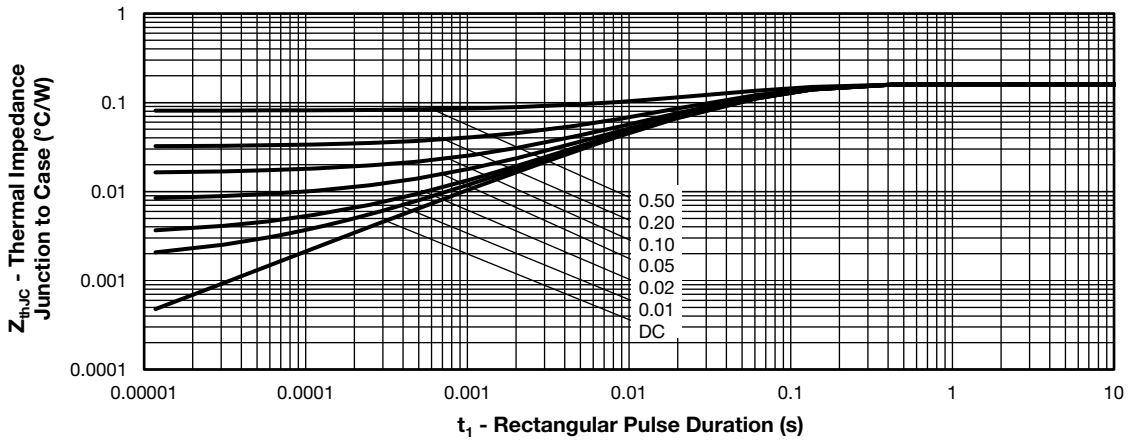


Fig. 19 - Maximum Trench IGBT Thermal Impedance Z_{thJC} Characteristics

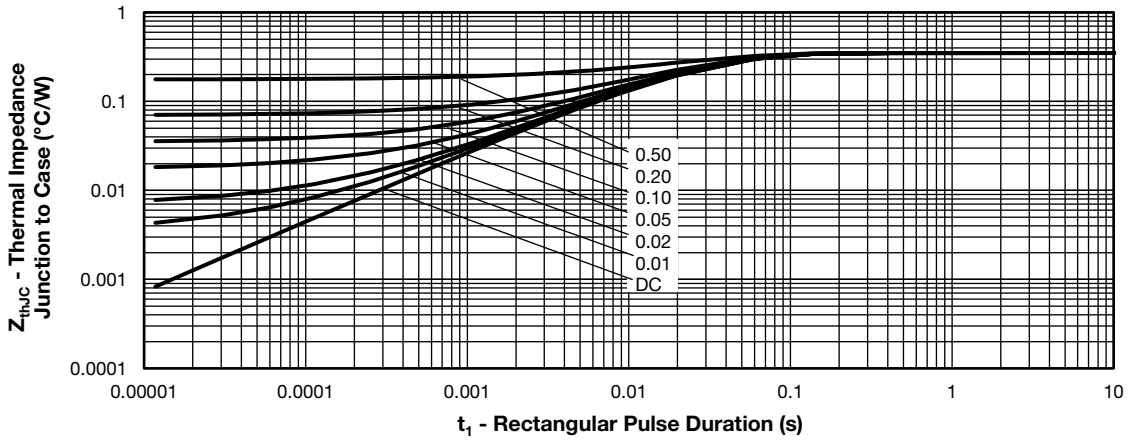


Fig. 20 - Maximum Antiparallel Diode Thermal Impedance Z_{thJC} Characteristics

For technical questions within your region: DiodesAmericas@vishay.com, DiodesAsia@vishay.com, DiodesEurope@vishay.com
THIS DOCUMENT IS SUBJECT TO CHANGE WITHOUT NOTICE. THE PRODUCTS DESCRIBED HEREIN AND THIS DOCUMENT ARE SUBJECT TO SPECIFIC DISCLAIMERS, SET FORTH AT www.vishay.com/doc?91000

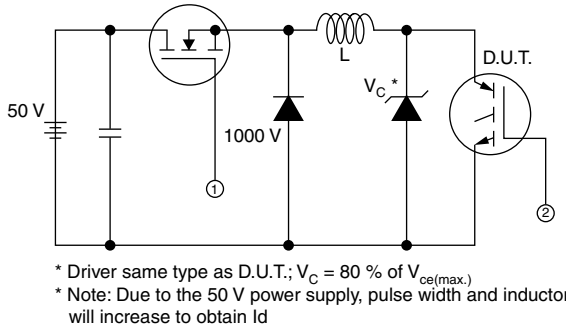


Fig. 21 - Clamped Inductive Load Test Circuit

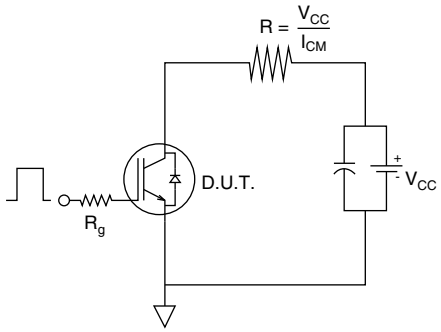


Fig. 22 - Pulsed Collector Current Test Circuit

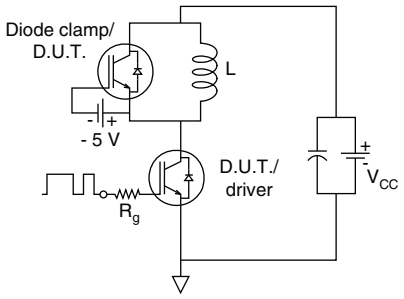


Fig. 23 - Switching Loss Test Circuit

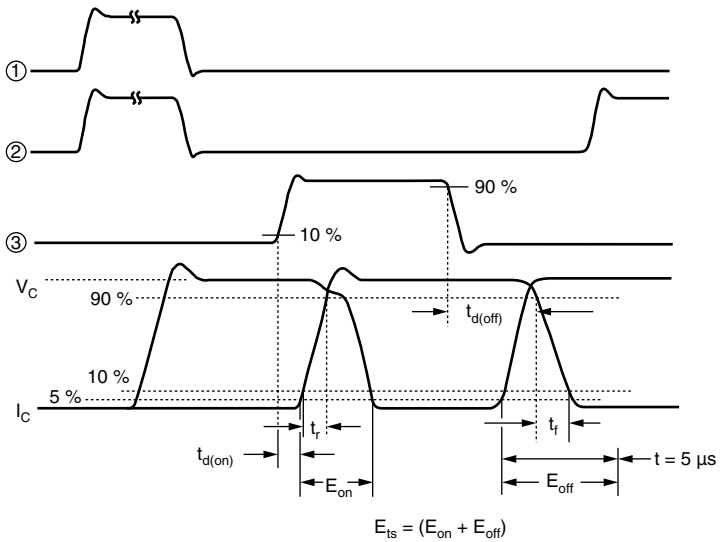


Fig. 24 - Switching Loss Waveforms Test Circuit

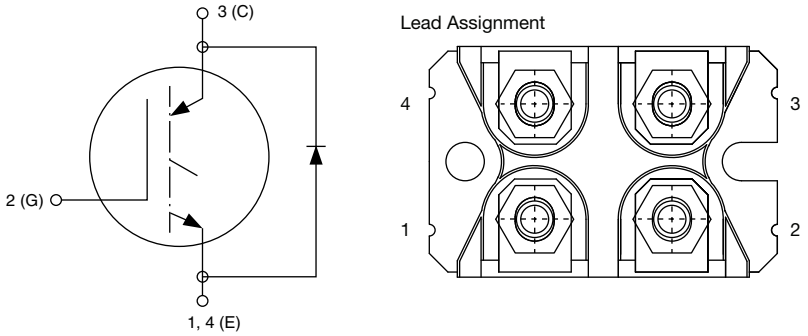
For technical questions within your region: DiodesAmericas@vishay.com, DiodesAsia@vishay.com, DiodesEurope@vishay.com
THIS DOCUMENT IS SUBJECT TO CHANGE WITHOUT NOTICE. THE PRODUCTS DESCRIBED HEREIN AND THIS DOCUMENT ARE SUBJECT TO SPECIFIC DISCLAIMERS, SET FORTH AT www.vishay.com/doc?91000

ORDERING INFORMATION TABLE

Device code

VS-	G	T	90	D	A	120	U
1	2	3	4	5	6	7	8

1	-	Vishay Semiconductors product
2	-	Insulated gate bipolar transistor (IGBT)
3	-	T = Trench IGBT
4	-	Current rating (90 = 90 A)
5	-	Circuit configuration (D = single switch with AP diode)
6	-	Package indicator (A = SOT-227)
7	-	Voltage rating (120 = 1200 V)
8	-	Speed/type (U = ultrafast IGBT)

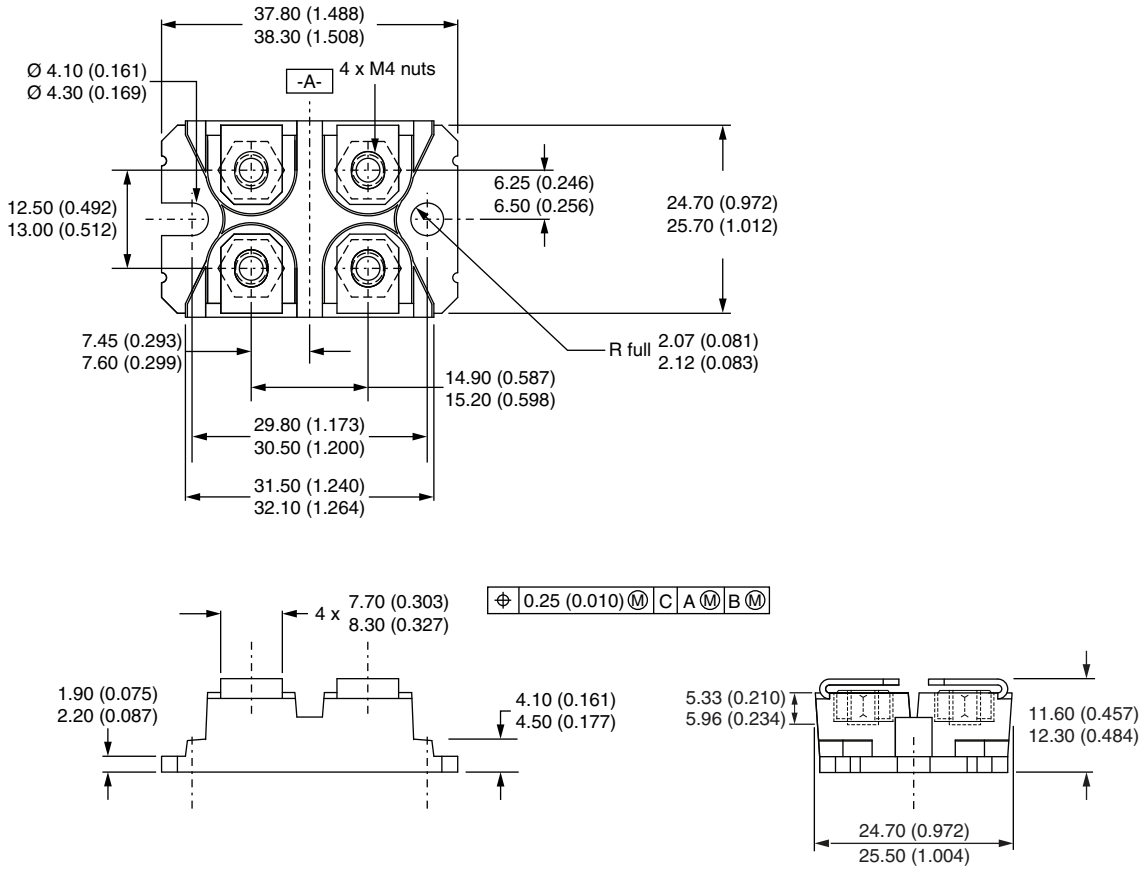
CIRCUIT CONFIGURATION		
CIRCUIT	**CIRCUIT CONFIGURATION CODE**	**CIRCUIT DRAWING**
Single switch with AP diode	D	

LINKS TO RELATED DOCUMENTS	
Dimensions	www.vishay.com/doc?95423
Packaging information	www.vishay.com/doc?95425

For technical questions within your region: DiodesAmericas@vishay.com, DiodesAsia@vishay.com, DiodesEurope@vishay.com
THIS DOCUMENT IS SUBJECT TO CHANGE WITHOUT NOTICE. THE PRODUCTS DESCRIBED HEREIN AND THIS DOCUMENT ARE SUBJECT TO SPECIFIC DISCLAIMERS, SET FORTH AT www.vishay.com/doc?91000

SOT-227 Generation 2

DIMENSIONS in millimeters (inches)



Note

- Controlling dimension: millimeter

For technical questions, contact: DiodesAmericas@vishay.com

THIS DOCUMENT IS SUBJECT TO CHANGE WITHOUT NOTICE. THE PRODUCTS DESCRIBED HEREIN AND THIS DOCUMENT ARE SUBJECT TO SPECIFIC DISCLAIMERS, SET FORTH AT www.vishay.com/doc?91000

Disclaimer

ALL PRODUCT, PRODUCT SPECIFICATIONS AND DATA ARE SUBJECT TO CHANGE WITHOUT NOTICE TO IMPROVE RELIABILITY, FUNCTION OR DESIGN OR OTHERWISE.

Vishay Intertechnology, Inc., its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, “Vishay”), disclaim any and all liability for any errors, inaccuracies or incompleteness contained in any datasheet or in any other disclosure relating to any product.

Vishay makes no warranty, representation or guarantee regarding the suitability of the products for any particular purpose or the continuing production of any product. To the maximum extent permitted by applicable law, Vishay disclaims (i) any and all liability arising out of the application or use of any product, (ii) any and all liability, including without limitation special, consequential or incidental damages, and (iii) any and all implied warranties, including warranties of fitness for particular purpose, non-infringement and merchantability.

Statements regarding the suitability of products for certain types of applications are based on Vishay's knowledge of typical requirements that are often placed on Vishay products in generic applications. Such statements are not binding statements about the suitability of products for a particular application. It is the customer's responsibility to validate that a particular product with the properties described in the product specification is suitable for use in a particular application. Parameters provided in datasheets and / or specifications may vary in different applications and performance may vary over time. All operating parameters, including typical parameters, must be validated for each customer application by the customer's technical experts. Product specifications do not expand or otherwise modify Vishay's terms and conditions of purchase, including but not limited to the warranty expressed therein.

Hyperlinks included in this datasheet may direct users to third-party websites. These links are provided as a convenience and for informational purposes only. Inclusion of these hyperlinks does not constitute an endorsement or an approval by Vishay of any of the products, services or opinions of the corporation, organization or individual associated with the third-party website. Vishay disclaims any and all liability and bears no responsibility for the accuracy, legality or content of the third-party website or for that of subsequent links.

Vishay products are not designed for use in life-saving or life-sustaining applications or any application in which the failure of the Vishay product could result in personal injury or death unless specifically qualified in writing by Vishay. Customers using or selling Vishay products not expressly indicated for use in such applications do so at their own risk. Please contact authorized Vishay personnel to obtain written terms and conditions regarding products designed for such applications.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document or by any conduct of Vishay. Product names and markings noted herein may be trademarks of their respective owners.

© 2026 VISHAY INTERTECHNOLOGY, INC. ALL RIGHTS RESERVED

THIS DOCUMENT IS SUBJECT TO CHANGE WITHOUT NOTICE. THE PRODUCTS DESCRIBED HEREIN AND THIS DOCUMENT ARE SUBJECT TO SPECIFIC DISCLAIMERS, SET FORTH AT www.vishay.com/doc?91000